

Abstract

An object of the present invention is to provide a multilayer wiring board of which it is possible to prevent warping and which has high reliability, and a method for manufacturing the multilayer wiring board. An example of the multilayer wiring board of the present invention includes: an inorganic substrate which has a first surface, a second surface opposite the first surface, and a lateral face connecting a peripheral edge portion of the first surface to a peripheral edge portion of the second surface, and which has formed therein at least one through hole penetrating from the first surface to the second surface; a protection resin portion disposed in the through hole of the inorganic substrate and disposed so as to cover the lateral face of the inorganic substrate; and a through electrode which includes a conductor portion extending inside the through hole and establishes an electric connection between the first surface and the second surface.